

FLEXIBLE

Deploy liquid, air or hybrid mixed liquid/air configurations

HIGH PERFORMANCE

Superior energy efficiency with fan optimization

MAXIMUM UPTIME

With redundant pumps and power supplies

ROBUST MANAGEMENT

via SNMP, Redfish, Web UI, and RESTful APIs



GigaIO Cooling Options

Comprehensive thermal management from air cooling to direct-to-chip liquid cooling

GigaIO offers a complete range of advanced cooling solutions designed to support the most demanding AI and HPC workloads. From traditional air cooling to cutting-edge direct-to-chip (D2C) liquid cooling, our thermal management portfolio ensures optimal performance, reliability and energy efficiency for SuperNODE deployments and high-density computing environments.



| | Air Cooled Racks | Rear Door Heat Exchanger (RDHXw) | In-Rack CDU | In-Row CDU | Liquid-to-air Sidecar (CDU) |
|--------------------------|-------------------------------|---|--|--|---|
| Cooling Capacity | Up to 35kW* | Up to 80kW | Up to 250kW | Up to 1.8MW | Up to 200kW |
| Power Dissipation | N/A | 3.3kW | 1.2kW | 20kW | 19kW |
| Supported GPUs** | PCIe GPUs | | | | |
| | MI350X OAM | | B300 SXM mixed air/liquid | | |
| | H200 SXM | | | | |
| Deployment Size | Any size | | < 8 racks | 8+ racks | 2 racks/unit |
| Dimensions | Standard 42U or 48U | 23.6" (or 31.2") W x 87.8" H x 17.7" D 600mm (or 800mm) W x 2230mm H x 450mm D | 4U: 18.9" W x 7.0" H x 45.7" D 480mm W x 177.8mm H x 1160.9mm D | 33.5" W x 90.6" H x 51.2" D 850.9mm W x 2301mm H x 1300.5mm D | 43.3" W x 78.7" H x 55.7" D 1099.8mm W x 1999mm H x 1414.8mm D |
| Weight | Varies | 330.7lbs 150kg | 220.5lbs 100kg | 2,646lbs 1200kg | 2,524lbs 1144.9kg |
| Infrastructure | Existing CRAC/CRAH | Facility water | | | Existing CRAC/CRAH |
| Key Features | Front-to-rear airflow | Passive heat exchanger, Retrofit ready | Redundant pumps | Floor-standing, N+1 pumps, Dual PSUs | Closed-loop, VFD fans, touchscreen |
| Best For | Standard density existing DCs | Retrofit density boost | Small clusters, Single racks | Large clusters, DC scale | Small deploy, No facility water |

* Rack power dependent on site infrastructure

** AMD MI355X and Nvidia B300 GPUs require Direct-to-Chip (D2C) liquid cooling. Rear door heat exchanger (RDHX) doors required when using D2C without CDU solutions